

Title of Change:	Backgrind site change from USR (onsemi Gresham) to MY2 (onsemi ISMF)
Effective date:	07 Nov 2023
Contact information:	Contact your local onsemi Sales Office or Melai.Obnial@onsemi.com
Type of notification:	This Product Bulletin is for notification purposes only. onsemi will proceed with implementation of this change upon publication of this Product Bulletin.
Change Category:	Wafer Fab Change
Change Sub-Category(s):	Manufacturing Site Transfer

Sites Affected:

onsemi Sites	External Foundry/Subcon Sites
onsemi, ISMF Malaysia	None

Description and Purpose:

onsemi would like to notify customer of a change in backgrind location for the devices listed in this Product Bulletin. Products are currently receiving backgrind in onsemi Gresham US, but will be moved to our center of excellence for backgrind at onsemi, ISMF Malaysia. Products produced on this technology, out of this onsemi Gresham, have been backgrinding in onsemi, ISMF Malaysia for > 10 years now.

	From	To
BACKGRIND	onsemi Gresham, USA	onsemi ISMF, Malaysia

List of Affected Standard Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

NCV300LSN28T1G	NCV300LSN36T1G	NCV301LSN22T1G
NCV301LSN28T1G	NCV301LSN33T1G	NCV301LSN40T1G
NCV301LSN42T1G	NCV303LSN09T1G	NCV303LSN10T1G
NCV303LSN11T1G	NCV303LSN16T1G	NCV303LSN20T1G
NCV303LSN24T1G	NCV303LSN25T1G	NCV303LSN27T1G
NCV303LSN46T1G	NCV303LSN45T1G	NCV303LSN44T1G
NCV303LSN42T1G	NCV303LSN40T1G	NCV303LSN34T1G
NCV303LSN31T1G	NCV303LSN30T1G	NCV303LSN29T1G